



N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^d	Q _g (Typ.)			
	0.028 at V _{GS} = 4.5 V	7.9				
20	0.032 at V _{GS} = 2.5 V	7.4	6.7 nC			
	0.038 at V _{GS} = 1.8 V	6.8				

TSOP-6 Top View

2.85 mm -

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

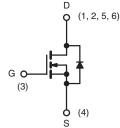


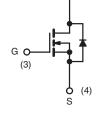
COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC Converters
- **Boost Converters**
- Load Switch

Lot Traceability and Date Code





Ordering Information: Si3460DDV-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 8	v	
	T _C = 25 °C		7.9		
Continuous Dunin Comment (T. 150 °C)	T _C = 70 °C	1 .	6.3		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	l _D	6.2 ^{a, b}		
	T _A = 70 °C	1	5.0 ^{a, b}		
Pulsed Drain Current		I _{DM}	20	A	
Continuous Course Dunin Diade Courset	T _C = 25 °C		2.2		
Continuous Source-Drain Diode Current	T _A = 25 °C	ls ls	1.4 ^{a, b}		
Avalanche Current		I _{AS}	8		
Single Avalanche Energy		E _{AS}	3.2	mJ	
	T _C = 25 °C		2.7		
Mariana Para Piasinatian	T _C = 70 °C		1.7	10/	
Maximum Power Dissipation	T _A = 25 °C	P _D	1.7 ^{a, b}	W	
	T _A = 70 °C		1.1 ^{a, b}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		
Soldering Recommendations (Peak Tempera		260	°C		

Marking Code BA XXX

Part # Code

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{a, c}	t ≤ 5 s	R _{thJA}	61	74	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	38	46	O/W		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 5 s.
- c. Maximum under steady state conditions is 120 °C/W.
- d. Based on $T_C = 25$ °C.

Si3460DDV

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static				1		
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 · A		21		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 2.6		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu\text{A}$	0.4		1.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
7 0		V _{DS} = 20 V, V _{GS} = 0 V			1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V, T _J = 70 °C			10	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α
	(* /	V _{GS} = 4.5 V, I _D = 5.1 A		0.023	0.028	Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 2.5 V, I _D = 4.7 A		0.027	0.032	
	- ()	V _{GS} = 1.8 V, I _D = 2.5 A		0.031	0.038	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 5.1 A		35		S
Dynamic ^b	<u> </u>	-				
Input Capacitance	C _{iss}			666		
Output Capacitance	C _{oss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		93		pF
Reverse Transfer Capacitance	C _{rss}	30		41		1 "
·	Q _g	V _{DS} = 10 V, V _{GS} = 8 V, I _D = 5 A		12	18	nC
Total Gate Charge				6.7	10.1	
Gate-Source Charge		$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		0.95		
Gate-Drain Charge	Q _{gd}			0.5		
Gate Resistance	R _g	f = 1 MHz	0.4	2.1	4.2	Ω
Turn-On Delay Time	t _{d(on)}			6	12	
Rise Time	t _r	$V_{DD} = 10 \text{ V}, R_1 = 2 \Omega$		11	20	ns
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		21	32	
Fall Time	t _f	•		8	16	
Turn-On Delay Time	t _{d(on)}			5	10	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2 Ω		12	18	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 8 \text{ V}, R_q = 1 \Omega$		19	29	
Fall Time	t _f	Ç		8	16	
Drain-Source Body Diode Characteristic	L L					
Continuous Source-Drain Diode Current I _S		T _C = 25 °C			2.2	
Pulse Diode Forward Current	I _{SM}	<u> </u>			20	A
Body Diode Voltage	V _{SD}	I _S = 5 A, V _{GS} = 0 V		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}	5 . 40		11	20	ns
Body Diode Reverse Recovery Charge	Q _{rr}			3	6	nC
Reverse Recovery Fall Time	t _a	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		7	-	ns
Reverse Recovery Rise Time	t _b		-	4		

Notes:

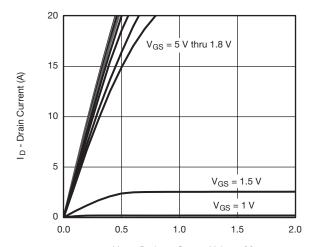
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %

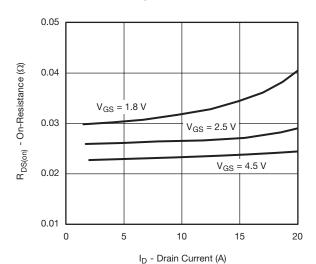
b. Guaranteed by design, not subject to production testing.



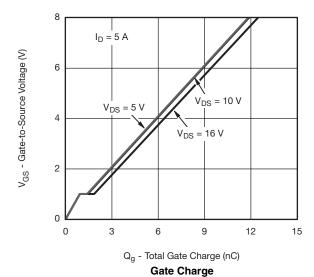
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

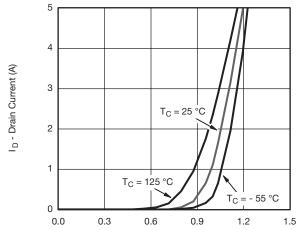


V_{DS} - Drain-to-Source Voltage (V) **Output Characteristics**

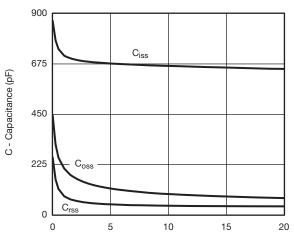


On-Resistance vs. Drain Current and Gate Voltage

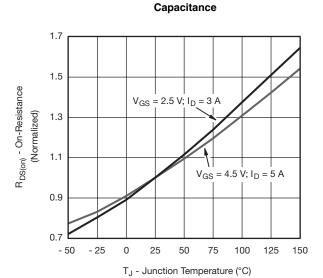




V_{GS} - Gate-to-Source Voltage (V) **Transfer Characteristics**



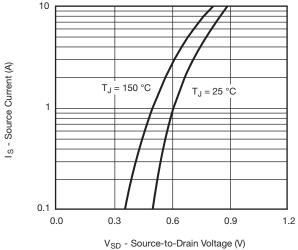
V_{DS} - Drain-to-Source Voltage (V)



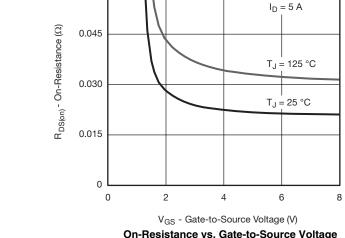
On-Resistance vs. Junction Temperature

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

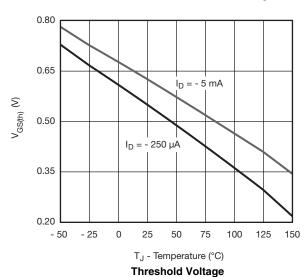


Source-Drain Diode Forward Voltage



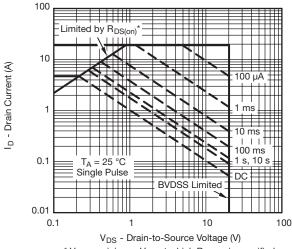
0.060

On-Resistance vs. Gate-to-Source Voltage



25 20 15 10 5 0 0.001 0.01 0.1 10 Time (s)

Single Pulse Power (Junction-to-Ambient)

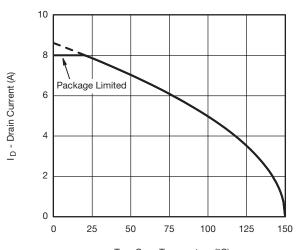


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

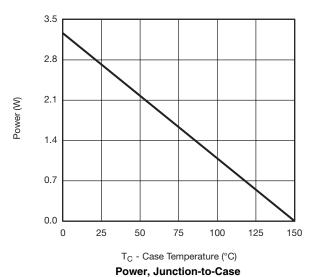


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

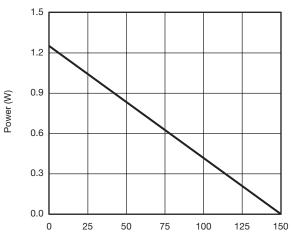


T_C - Case Temperature (°C)

Current Derating*







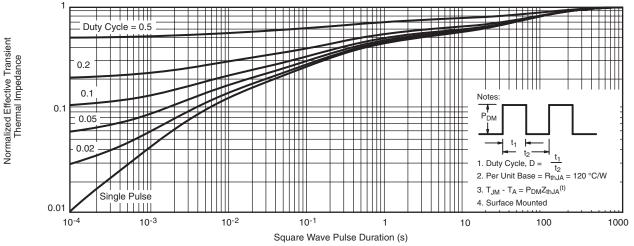
T_A - Ambient Temperature (°C) Power, Junction-to-Ambient

 $^{^*}$ The power dissipation P_D is based on $T_{J(max.)}$ = 150 $^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

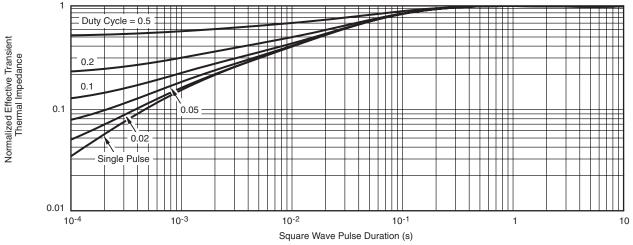
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppq?66572.





TSOP: 5/6-LEAD

JEDEC Part Number: MO-193C





5-LEAD TSOP







	MILLIMETERS INCHES						
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A ₁	0.01	-	0.10	0.0004	-	0.004	
A ₂	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.008		
D	2.95	3.05	3.10	0.116	0.122		
E	2.70	2.85	2.98	0.106	0.112	0.117	
E ₁	1.55	1.65	1.70	0.061	0.065	0.067	
е	0.95 BSC			0.0374 BSC			
e ₁	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L ₁	0.60 Ref			0.024 Ref			
L ₂	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
θ1	7° Nom			7° Nom			
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							

DWG: 5540

Document Number: 71200 18-Dec-06



Recommended Land Pattern For TSOP-5L / TSOP-6L



Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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